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Texas Instruments
TL5002CD

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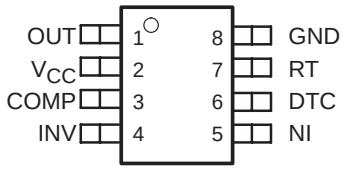
TL5002
PULSE-WIDTH-MODULATION CONTROL CIRCUIT

SLVS304A − SEPTEMBER 2000 − REVISED AUGUST 2002

- Complete PWM Power Control
- 3.6-V to 40-V Operation
- Internal Undervoltage-Lockout Circuit
- Oscillator Frequency . . . 20 kHz to 500 kHz
- Variable Dead Time Provides Control Over Total Range
- Ideal Controller for DDR Memory Application
- Uncommitted Error Amplifier Inputs

D PACKAGE
(TOP VIEW)



description

The TL5002 incorporates on a single monolithic chip all the functions required for a pulse-width-modulation (PWM) control circuit. Designed primarily for power-supply control, the TL5002 contains an error amplifier, a regulator, an oscillator, a PWM comparator with a dead-time-control input, undervoltage lockout (UVLO), and an open-collector output transistor.

The error-amplifier input common-mode voltage ranges from 0.9 V to 1.5 V. Dead-time control (DTC) can be set to provide 0% to 100% dead time by connecting an external resistor between DTC and GND. The oscillator frequency is set by terminating RT with an external resistor to GND. During low V_{CC} conditions, the UVLO circuit turns the output off until V_{CC} recovers to its normal operating range.

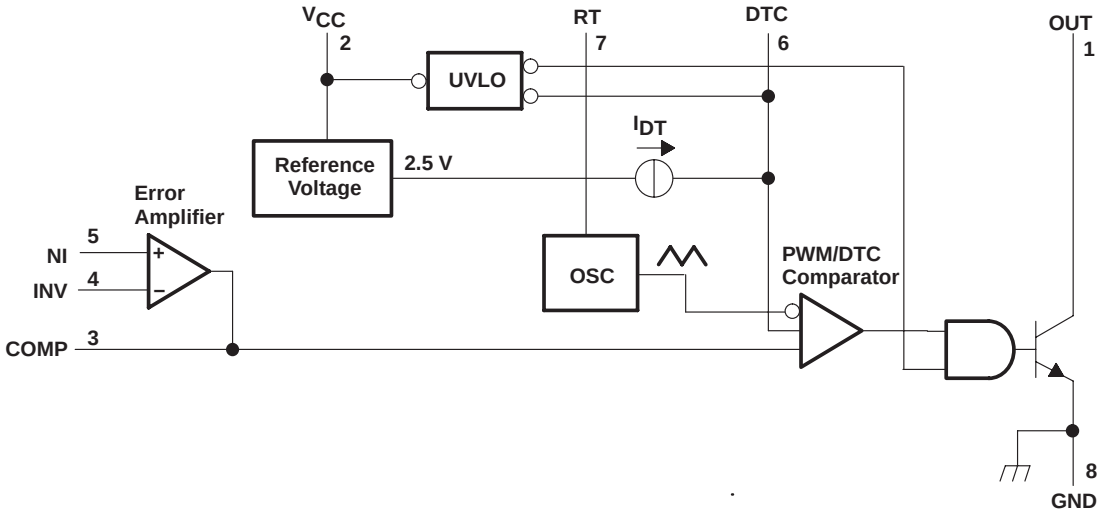
The TL5002 is characterized for operation from −40°C to 85°C.

AVAILABLE OPTIONS

T_A	SMALL OUTLINE (D)
−20°C to 85°C	TL5002CD
−40°C to 85°C	TL5002ID

The D package is available taped and reeled. Add the suffix R to the device type (e.g., TL5002CDR).

functional block diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

detailed description

voltage reference

A 2.5-V regulator operating from V_{CC} is used to power the internal circuitry of the TL5002.

error amplifier

The error amplifier compares a sample of the dc-to-dc converter output voltage to an external reference voltage and generates an error signal for the PWM comparator. The dc-to-dc converter output voltage is set by selecting the error-amplifier gain (see Figure 1), using the following expression:

$$V_O = (1 + R1/R2)\ (1\ V)$$

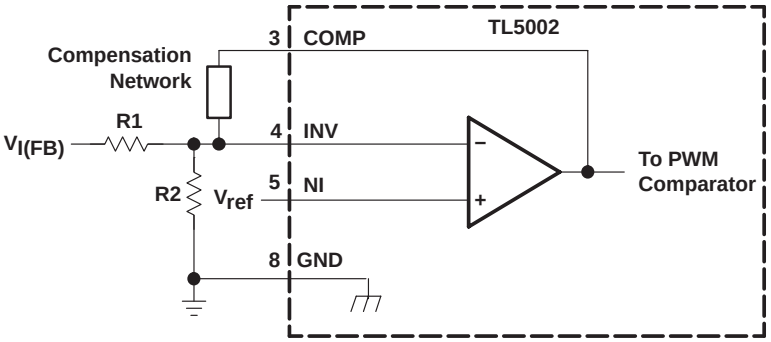


Figure 1. Error-Amplifier Gain Setting

The error-amplifier output is brought out as COMP for use in compensating the dc-to-dc converter control loop for stability. Because the amplifier can only source 45 μA, the total dc load resistance should be 100 kΩ or more.

oscillator/PWM

The oscillator frequency (f_{osc}) can be set between 20 kHz and 500 kHz by connecting a resistor between RT and GND. Acceptable resistor values range from 15 kΩ to 250 kΩ. The oscillator frequency can be determined by using the graph shown in Figure 5.

The oscillator output is a triangular wave with a minimum value of approximately 0.7 V and a maximum value of approximately 1.3 V. The PWM comparator compares the error-amplifier output voltage and the DTC input voltage to the triangular wave and turns the output transistor off whenever the triangular wave is greater than the lesser of the two inputs.

dead-time control (DTC)

DTC provides a means of limiting the output-switch duty cycle to a value less than 100%, which is critical for boost and flyback converters. A current source generates a reference current (I_{DT}) at DTC that is nominally equal to the current at the oscillator timing terminal, RT. Connecting a resistor between DTC and GND generates a dead-time reference voltage (V_{DT}), which the PWM/DTC comparator compares to the oscillator triangle wave as described in the previous section. Nominally, the maximum duty cycle is 0% when V_{DT} is 0.7 V or less and 100% when V_{DT} is 1.3 V or greater. Because the triangle wave amplitude is a function of frequency and the source impedance of RT is relatively high (1250 Ω), choosing R_{DT} for a specific maximum duty cycle, D, is accomplished using the following equation and the voltage limits for the frequency in question as found in Figure 11 (V_{osc}max and V_{osc}min are the maximum and minimum oscillator levels):

dead-time control (DTC) (continued)

$$R_{DT} = \left(R_t + 1250\right)\left[D\left(V_{osc}max - V_{osc}min\right) + V_{osc}min\right]$$

Where

R_{DT} and R_t are in ohms, D in decimal

Soft start can be implemented by paralleling the DTC resistor with a capacitor (C_{DT}) as shown in Figure 2. During soft start, the voltage at DTC is derived by the following equation:

$$V_{DT} \approx I_{DT}R_{DT}\left(1 - e^{\left(-t/R_{DT}C_{DT}\right)}\right)$$

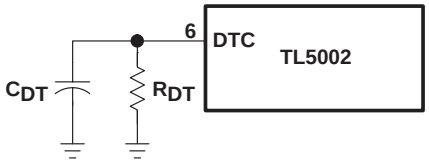


Figure 2. Soft-Start Circuit

If the dc-to-dc converter must be in regulation within a specified period of time, the time constant, $R_{DT}C_{DT}$, should be $t_0/3$ to $t_0/5$. The TL5002 remains off until $V_{DT} \approx 0.7$ V, the minimum ramp value. C_{DT} is discharged every time UVLO becomes active.

undervoltage-lockout (UVLO) protection

The undervoltage-lockout circuit turns the output transistor off whenever the supply voltage drops too low (approximately 3 V at 25°C) for proper operation. A hysteresis voltage of 200 mV eliminates false triggering on noise and chattering.

output transistor

The output of the TL5002 is an open-collector transistor with a maximum collector current rating of 21 mA and a voltage rating of 51 V. The output is turned on under the following conditions: the oscillator triangle wave is lower than both the DTC voltage and the error-amplifier output voltage, and the UVLO circuit is inactive.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 41 V
Amplifier input voltage, $V_{I(INV)}$, $V_{I(NI)}$ . . . . . 20 V
Output voltage, V_O, OUT . . . . . 51 V
Output current, I_O, OUT . . . . . 21 mA
Output peak current, $I_{O(peak)}$, OUT . . . . . 100 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating ambient temperature range, T_A . . . . . −40°C to 85°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC}	3.6	40	V
Amplifier input voltage, $V_{I(INV)}$, $V_{I(NI)}$	0.9	1.5	V
Output voltage, V_O, OUT		50	V
Output current, I_O, OUT		20	mA
COMP source current		45	µA
COMP dc load resistance	100		kΩ
Oscillator timing resistor, R_t	15	250	kΩ
Oscillator frequency, f_{osc}	20	500	kHz
Operating ambient temperature, T_A	−40	85	°C

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 6 V, f_{osc} = 100 kHz (unless otherwise noted)

undervoltage lockout

PARAMETER	TEST CONDITIONS	TL5002C			UNIT
		MIN	TYP†	MAX	
Upper threshold voltage	T_A = 25°C		3		V
Lower threshold voltage	T_A = 25°C		2.8		V
Hysteresis	T_A = 25°C	100	200		mV

† All typical values are at T_A = 25°C.

oscillator

PARAMETER	TEST CONDITIONS	TL5002C			UNIT
		MIN	TYP†	MAX	
Frequency	R_t = 100 kΩ		100		kHz
Standard deviation of frequency			15		kHz
Frequency change with voltage	V_{CC} = 3.6 V to 40 V		1		kHz
Frequency change with temperature	T_A = −40°C to 25°C	−4	−0.4	4	kHz
	T_A = −20°C to 25°C	−4	−0.4	4	kHz
	T_A = 25°C to 85°C	−4	−0.2	4	kHz
Voltage at RT			1		V

† All typical values are at T_A = 25°C.

dead-time control

PARAMETER		TEST CONDITIONS	TL5002C			UNIT
			MIN	TYP†	MAX	
Output (source) current	TL5002	$V_{(DT)}$ = 1.5 V	0.9 × I_{RT}‡		1.2 × I_{RT}	μA
Input threshold voltage		Duty cycle = 0%	0.5	0.7		V
		Duty cycle = 100%		1.3	1.5	

† All typical values are at T_A = 25°C.
‡ Output source current at RT

error amplifier

PARAMETER		TEST CONDITIONS	TL5002C			UNIT
			MIN	TYP†	MAX	
Input voltage		V_{CC} = 3.6 V to 40 V	0.3		1.5	V
Input bias current				−160	−500	nA
Output voltage swing	Positive		1.5	2.3		V
	Negative			0.3	0.4	V
Open-loop voltage amplification				80		dB
Unity-gain bandwidth				1.5		MHz
Output (sink) current		$V_{I(INV)}$ = 1.2 V, COMP = 1 V	100	600		μA
Output (source) current		$V_{I(INV)}$ = 0.8 V, COMP = 1 V	−45	−70		μA

† All typical values are at T_A = 25°C.

electrical characteristics over recommended operating free-air temperature range, V_{CC} = 6 V, f_{osc} = 100 kHz (unless otherwise noted) (continued)

output

PARAMETER	TEST CONDITIONS	TL5002C			UNIT
		MIN	TYP†	MAX	
Output saturation voltage	I_O = 10 mA		1.5	2	V
Off-state current	V_O = 50 V, V_{CC} = 0			10	µA
	V_O = 50 V			10	
Short-circuit output current	V_O = 6 V		40		mA

† All typical values are at T_A = 25°C.

total device

PARAMETER		TEST CONDITIONS	TL5002C			UNIT
			MIN	TYP†	MAX	
Standby supply current	Off state			1	1.5	mA
Average supply current		R_t = 100 kΩ		1.4	2.1	mA

† All typical values are at T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

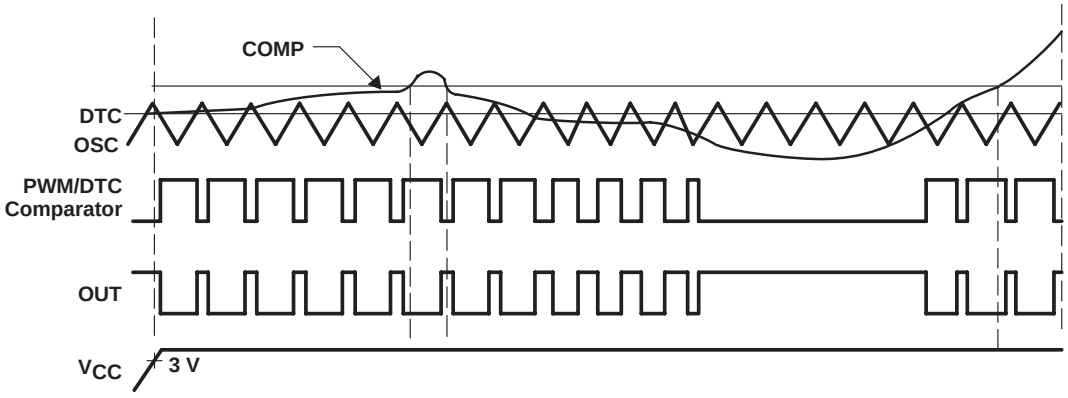


Figure 3. PWM Timing Diagram

TYPICAL CHARACTERISTICS

OSCILLATOR FREQUENCY
vs
TIMING RESISTANCE

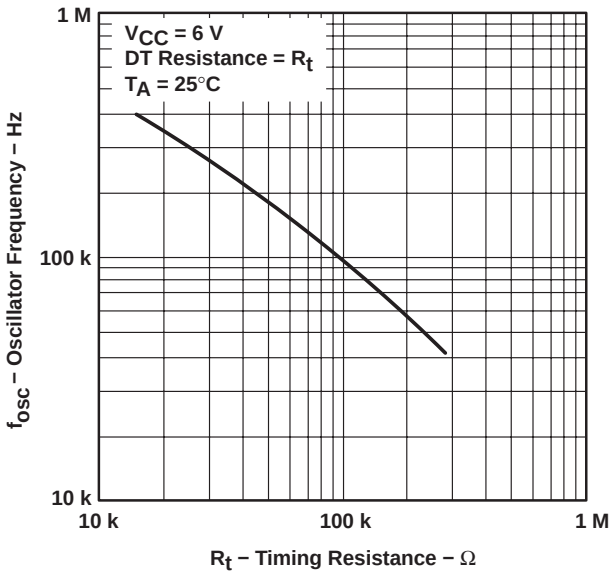


Figure 4

OSCILLATION FREQUENCY
vs
AMBIENT TEMPERATURE

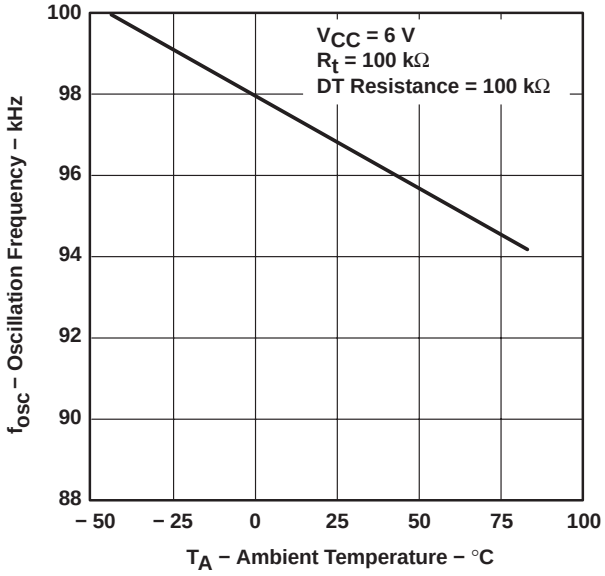


Figure 5

AVERAGE SUPPLY CURRENT
vs
POWER-SUPPLY VOLTAGE

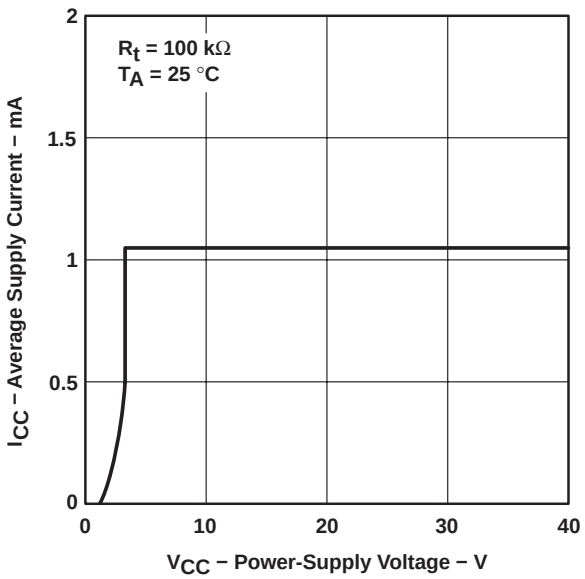


Figure 6

AVERAGE SUPPLY CURRENT
vs
AMBIENT TEMPERATURE

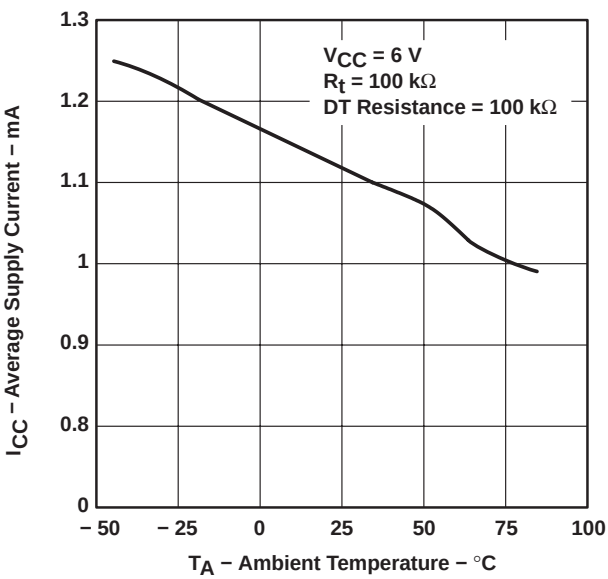


Figure 7

TYPICAL CHARACTERISTICS

PWM TRIANGLE WAVE AMPLITUDE VOLTAGE
vs
OSCILLATOR FREQUENCY

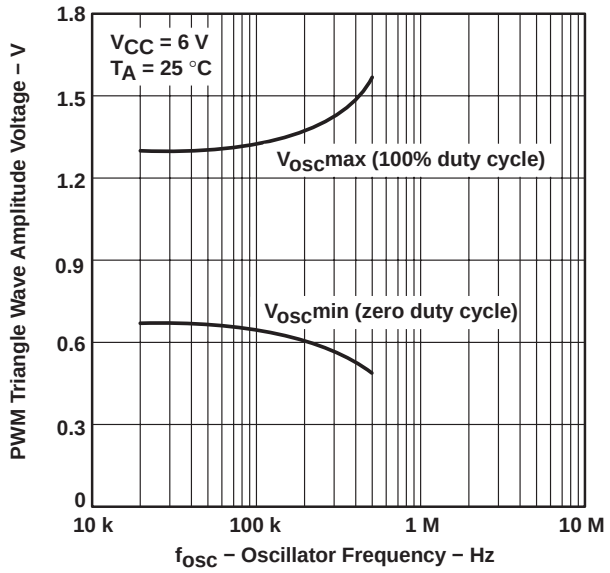


Figure 8

ERROR AMPLIFIER OUTPUT VOLTAGE
vs
OUTPUT (SINK) CURRENT

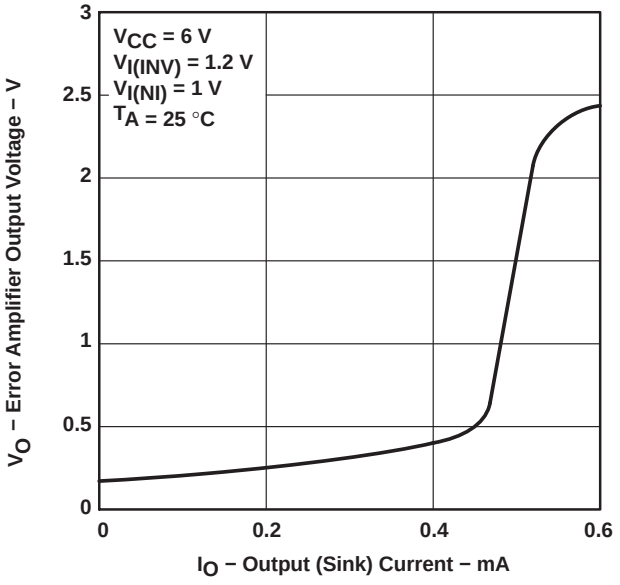


Figure 9

ERROR AMPLIFIER OUTPUT VOLTAGE
vs
OUTPUT (SOURCE) CURRENT

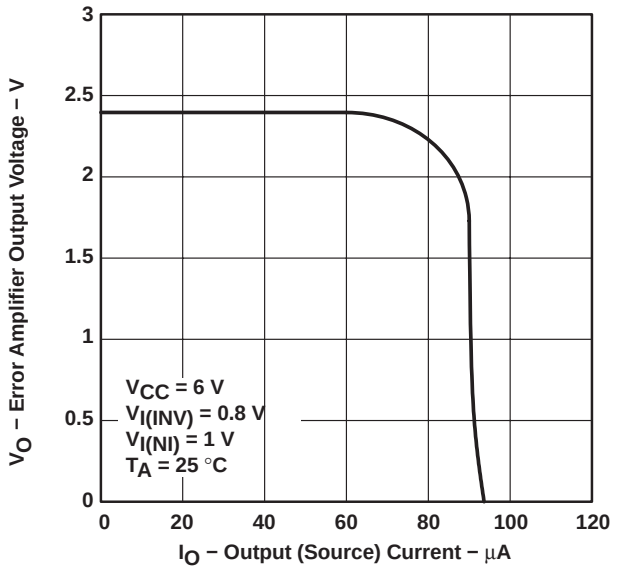


Figure 10

ERROR AMPLIFIER OUTPUT VOLTAGE
vs
AMBIENT TEMPERATURE

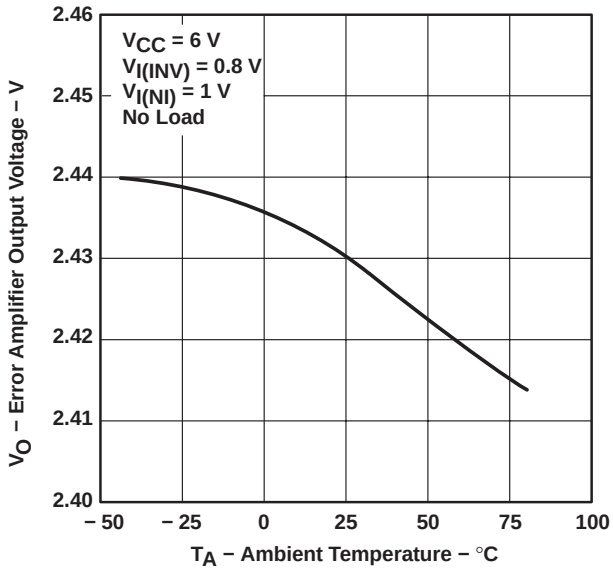


Figure 11

TYPICAL CHARACTERISTICS

ERROR AMPLIFIER OUTPUT VOLTAGE
vs
AMBIENT TEMPERATURE

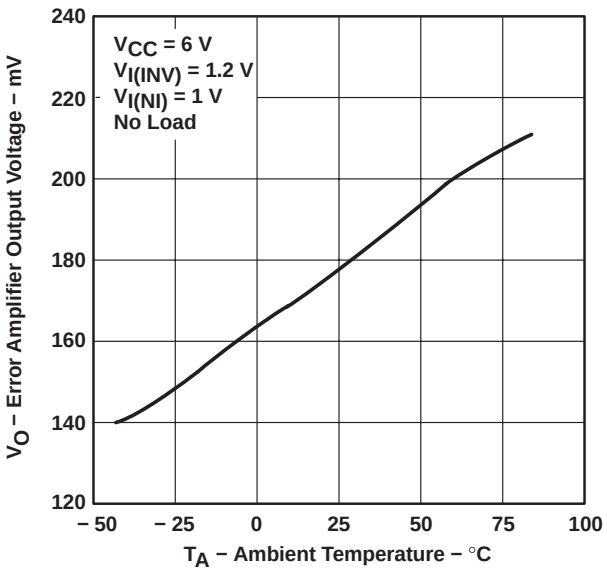


Figure 12

OUTPUT DUTY CYCLE
vs
DTC VOLTAGE

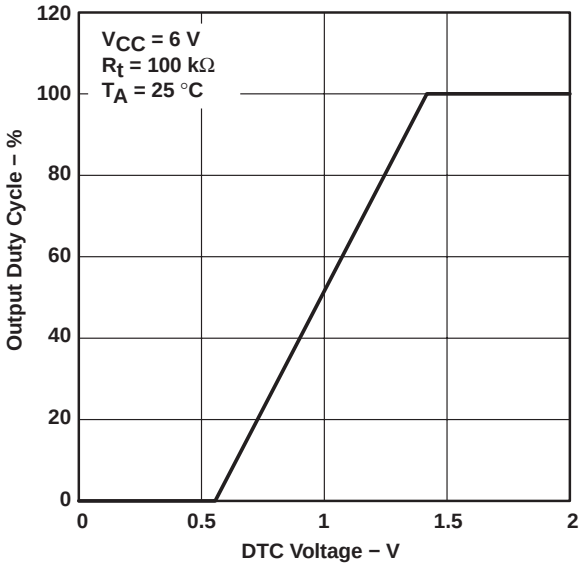


Figure 13

ERROR AMPLIFIER CLOSED-LOOP GAIN AND
PHASE SHIFT
vs
FREQUENCY

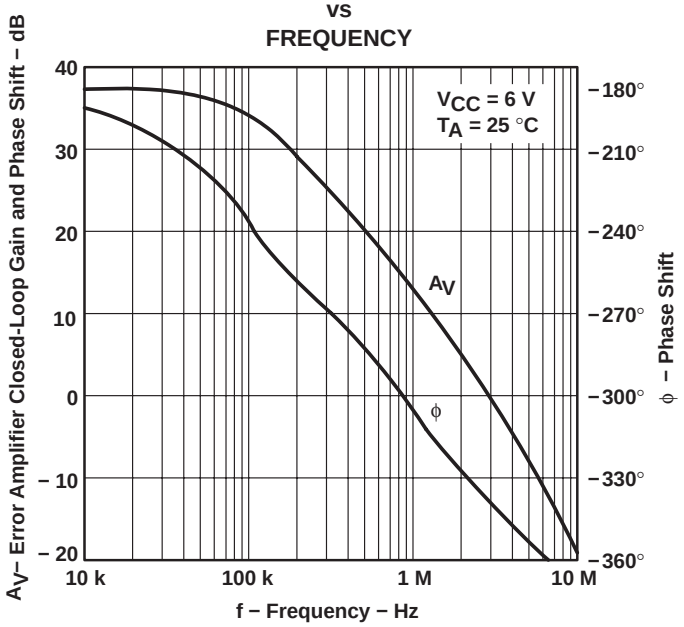


Figure 14

TYPICAL CHARACTERISTICS

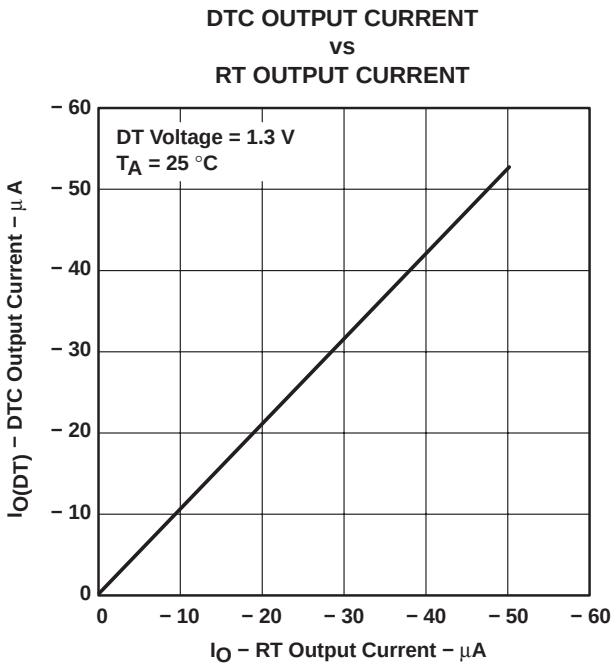


Figure 15

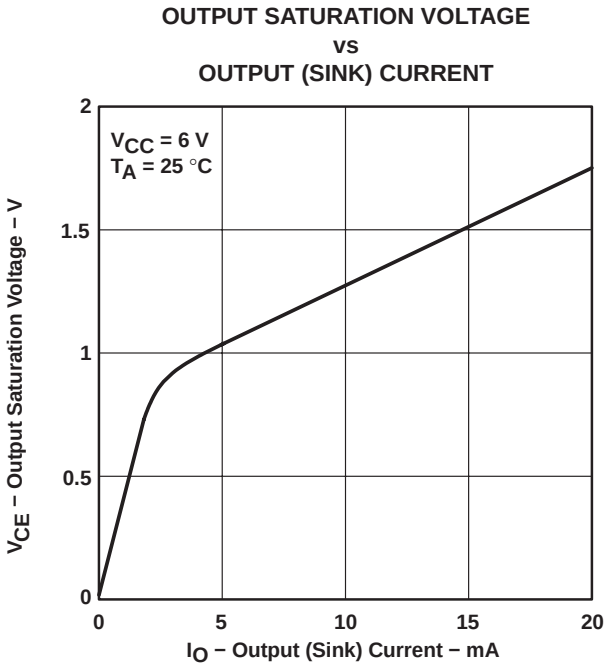


Figure 16

APPLICATION INFORMATION

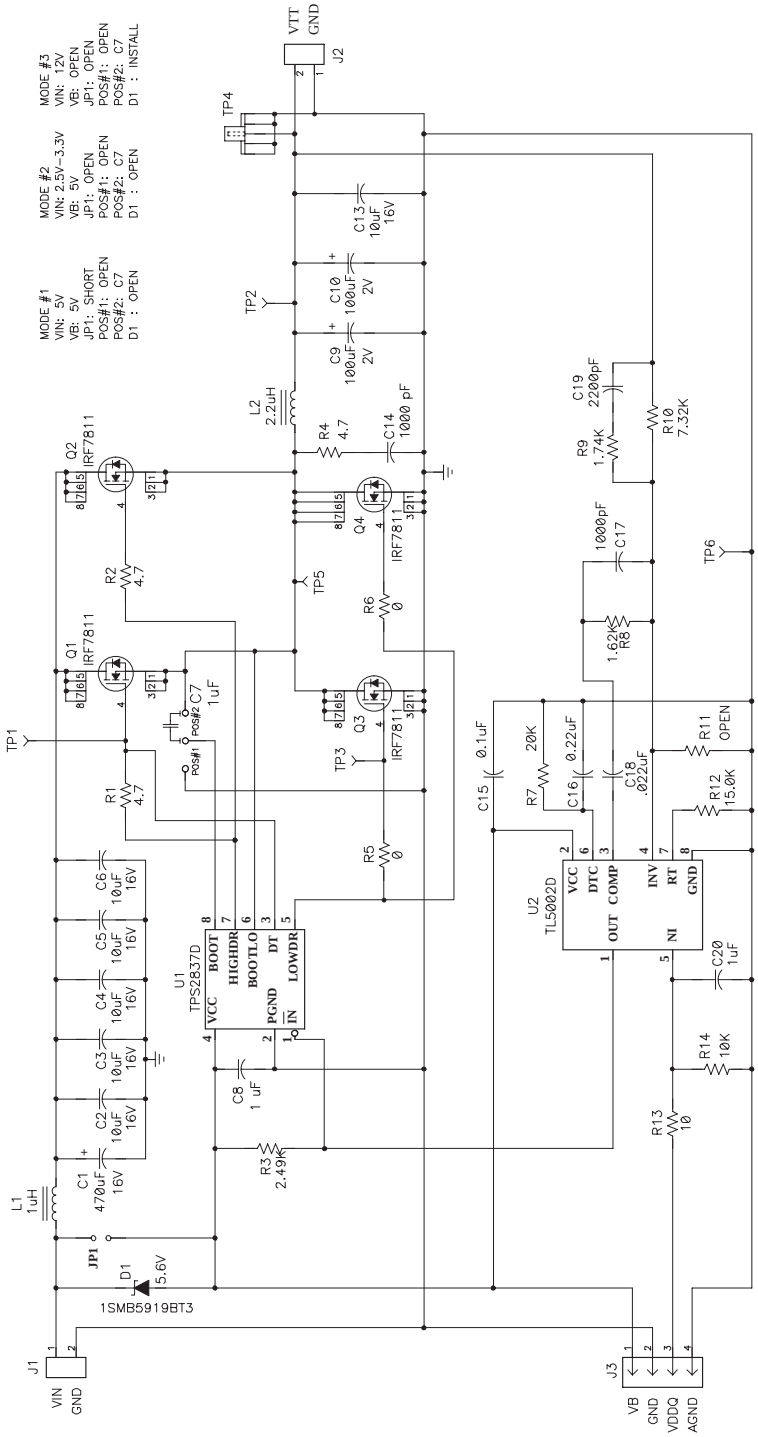


Figure 17. DDRI Application

APPLICATION INFORMATION

PARTIAL BILL OF MATERIALS

QUANTITY	REF DES	PART NUMBER	DESCRIPTION	MANUFACTURER	SIZE
1	C1	UUD1C471MNR1GS	Capacitor, aluminum	Nichicon	0.327 x 0.327
6	C2 − C6, C13	EMK325BJ106MN−B	Capacitor, ceramic	Taiyo Yuden	1210
3	C7, C8, C20	GRM40X7R105K16PT	Capacitor, ceramic, jumper	Murata	805
2	C9, C10	EEF−CD0D101R	Capacitor, aluminum	Panasonic	7343
1	C14	08055A102JAT2A	Capacitor, ceramic	AVX	805
1	C15	GRM39X7R104K016D	Capacitor, ceramic	Murata	603
1	C16	NMC0805X7R224K16TR	Capacitor, ceramic	NIP	603
1	C17	VJ0603Y222KXANT	Capacitor, ceramic	Murata	603
1	C18	C0603C223J3RACTU	Capacitor, ceramic	Kemet	603
1	C19	GRM39X7R223K16	Capacitor, ceramic	Murata	603
1	D1	1SMB5919BT3	Diode, zener, 5.6 V	On Semi	SMB
2	J1, J2	ED1609	Terminal block, 2-pin	OST	
1	J3	PTC36SAAN	Header, 4-pin	Sullins	
1	JP1	PTC36SAAN	Header, 2-pin	Sullins	
1	L1	UP2B−1R0	Inductor, SMT	Coiltronics	0.55 x 0.41
1	L2	UP4B−2R2	Inductor, SMT	Coiltronics	
4	Q1 − Q4	IRF7811	MOSFET, N−ch, 30 V	IR	SO8
3	R1, R2, R4	Std	Resistor, chip, 4.7 Ω	Std	603
1	R3	Std	Resistor, chip, 2.49 KΩ	Std	603
2	R5, R6	Std	Resistor, chip, 0 Ω	Std	603
1	R7	Std	Resistor, chip, 20 KΩ	Std	603
1	R8	Std	Resistor, chip, 162 KΩ	Std	603
1	R9	Std	Resistor, chip, 1.74 KΩ	Std	603
1	R10	Std	Resistor, chip, 7.32 KΩ	Std	603
1	R11	Std	Open	Std	603
1	R12	Std	Resistor, chip, 15 KΩ	Std	603
1	R13	Std	Resistor, chip, 10 Ω	Std	603
1	R14	Std	Resistor, chip, 10 KΩ	Std	603
4	TP1 − TP3, TP5	240-345	Test point, red, 1 mm	Farnell	0.038
1	TP4	131-4244-00 or 131-5031-00	Adaptor, 3.5 mm probe	Tektronix	0.200
1	TP6	1045-3-17-15-30-14-02-0	Post, wirewrap	Mill-Max	0.043
1	U1	TPS2837D	IC, MOSFET driver	Texas Instruments	SO8
1	U2	TL5002D	IC, low-cost PMW	Texas Instruments	SO8

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL5002CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	5002CD	Samples
TL5002CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	5002CD	Samples
TL5002CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-20 to 85	5002CD	Samples
TL5002ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	5002ID	Samples
TL5002IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	5002ID	Samples
TL5002IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	5002ID	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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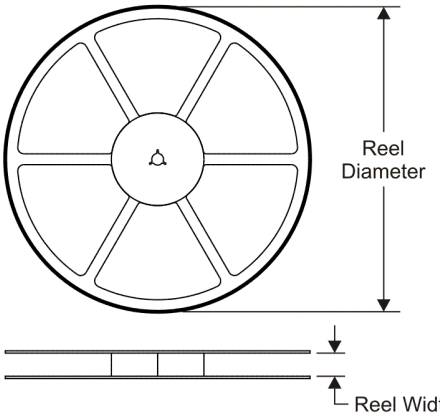
PACKAGE MATERIALS INFORMATION

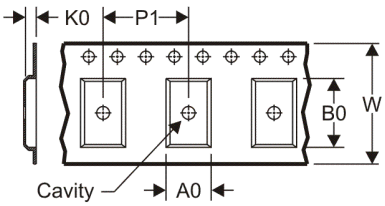
19-Mar-2008

TAPE AND REEL INFORMATION

REEL DIMENSIONS

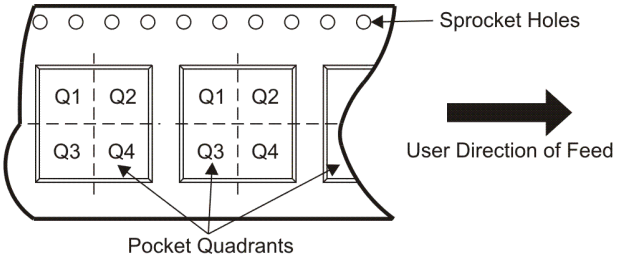


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



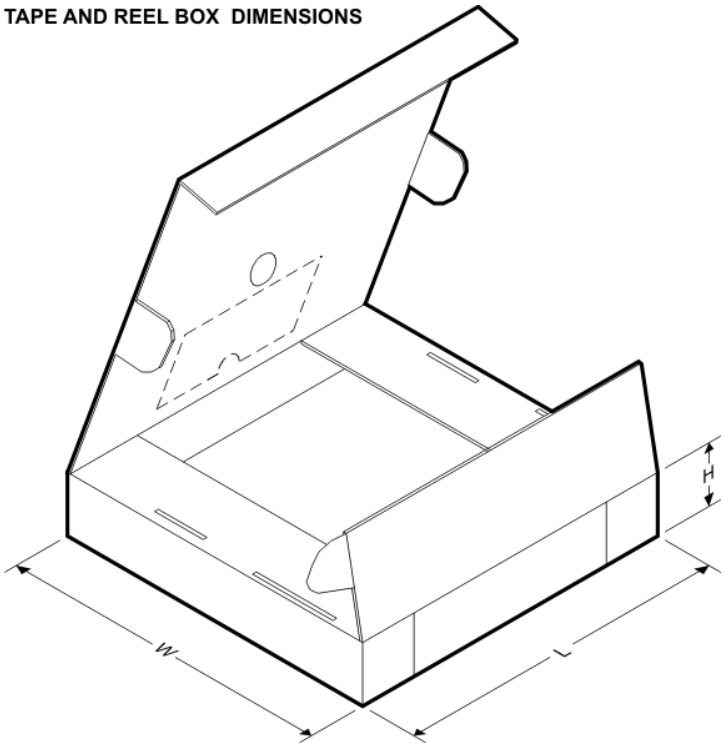
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL5002CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL5002IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

19-Mar-2008

TAPE AND REEL BOX DIMENSIONS

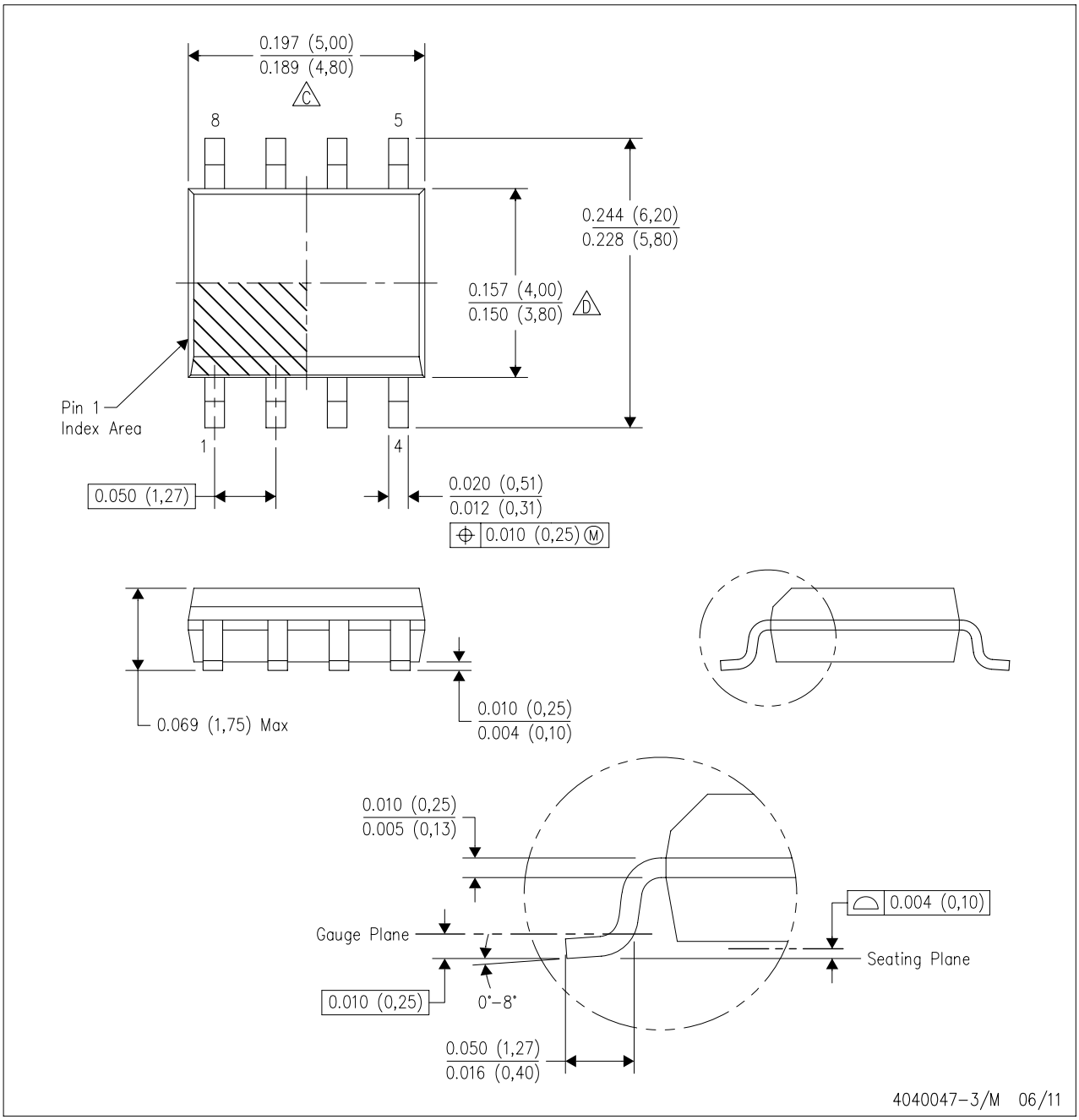


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL5002CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL5002IDR	SOIC	D	8	2500	340.5	338.1	20.6

MECHANICAL DATA

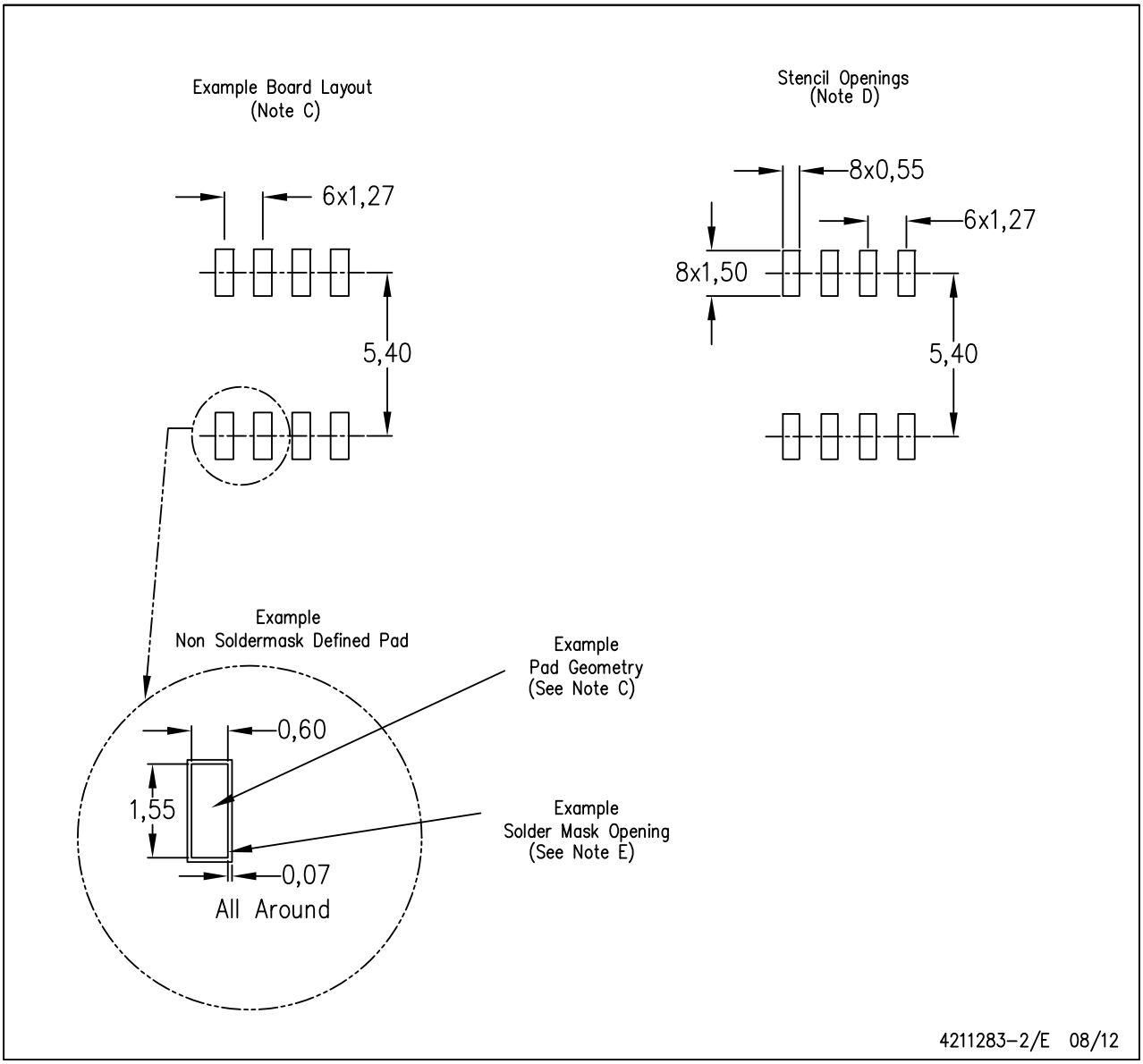
D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

LAND PATTERN DATA

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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